

SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING THE SAME

ABSTRACT

A semiconductor package and a method for fabricating the same are proposed, in which a lead frame is modified to form protrusions at sides of middle portions of leads to reduce spacing between the adjacent middle portions. This allows resin flow to slow down in speed during molding and reduces area available for resin flashes occurring thereon, so as to effectively eliminate the occurrence of resin flashes on the leads. Moreover, tapes can be adhered onto the lead frame for covering spacing between adjacent leads of the lead frame; this further helps prevent resin flashes from occurrence. In such an environment free of resin flashes, die-bonding and wire-bonding processes can be proceeded smoothly with assurance of quality and reliability of fabricated semiconductor packages.

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